

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Kelkar et al.

Attorney Docket No.: NSC1P181/P04767

Application No.: 09/653,925

Examiner: Parekh, N.

Filed: September 1, 2000

Group: 2811

Title: WAFER LEVEL CHIP SCALE
PACKAGE



CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail to: Commissioner for Patents, Washington, DC 20231 on July 17, 2002.

Signed:

Lara M. Nelson

Lara M. Nelson

AMENDMENT TRANSMITTAL

Commissioner for Patents
Washington, DC 20231

BEST AVAILABLE COPY

Sir:

Transmitted herewith is an Amendment in the above-identified application.

The fee has been calculated as shown below.

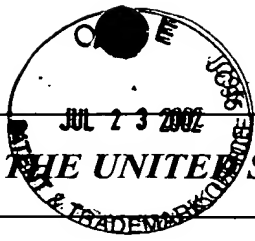
	Claims After Amendment		Highest Previously Paid For	Present Extra	Small Entity Rate Fee	Large Entity Rate Fee
Total Claims	19	MINUS	20	00	x 9 =	x 18 =
Independent Claims	02	MINUS	03	00	x 42 =	x 84 =
Multiple Dependent Claim Present and Fee Not Previously Paid					\$140.00	\$280.00
Total					\$	\$

- ☐ Applicant(s) hereby petition for a _____ month extension(s) of time to respond to the aforementioned Office Action.
- ☒ Applicant(s) believe that no (additional) Extension of Time is required; however, if it is determined that such an extension is required, Applicant(s) hereby petition that such an extension be granted and authorize the Commissioner to charge the required fees for an Extension of Time under 37 CFR 1.136 to Deposit Account No. 500388.
- ☐ Enclosed is our Check No. _____ in the amount of \$_____ to cover the additional claim fee and/or extension of time fees.
- ☒ Please charge the required fees, or any additional fees required to facilitate filing the enclosed response, to Deposit Account No. 500388 (Order No. NSC1P181).

Respectfully submitted,
BEYER WEAVER & THOMAS, LLP

Steve D Beyer
Steve D Beyer
Reg. No. 31,234

P.O. Box 778
Berkeley, CA 94704-0778



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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: KELKAR et al.

Application No.: 09/653,925

Filed: September 1, 2000

Title: WAFER LEVEL CHIP SCALE PACKAGE

Attorney Docket No.:
NSC1P181/P04767

Examiner: Parekh, N.

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I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail to: Commissioner for Patents, Washington, D.C. 20231 on July 17, 2002.

Signed: Lara M. Nelson
Lara M. Nelson

AMENDMENT A

Commissioner for Patents
Washington, DC 20231

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Dear Sir:

In response to the office action dated April 22, 2002, please enter the following amendments and remarks: